

# SOT386-1

plastic thin quad flat package; 100 leads; body 14 x 14 x 1 mm

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	Q (quad)
<b>Package type descriptive code</b>	TQFP100
<b>Package type industry code</b>	TQFP100
<b>Package style descriptive code</b>	TQFP (thin quad flat package)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>IEC package outline code</b>	137E20
<b>JEDEC package outline code</b>	MS-026
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	25-2-2003

Table 1. Package summary

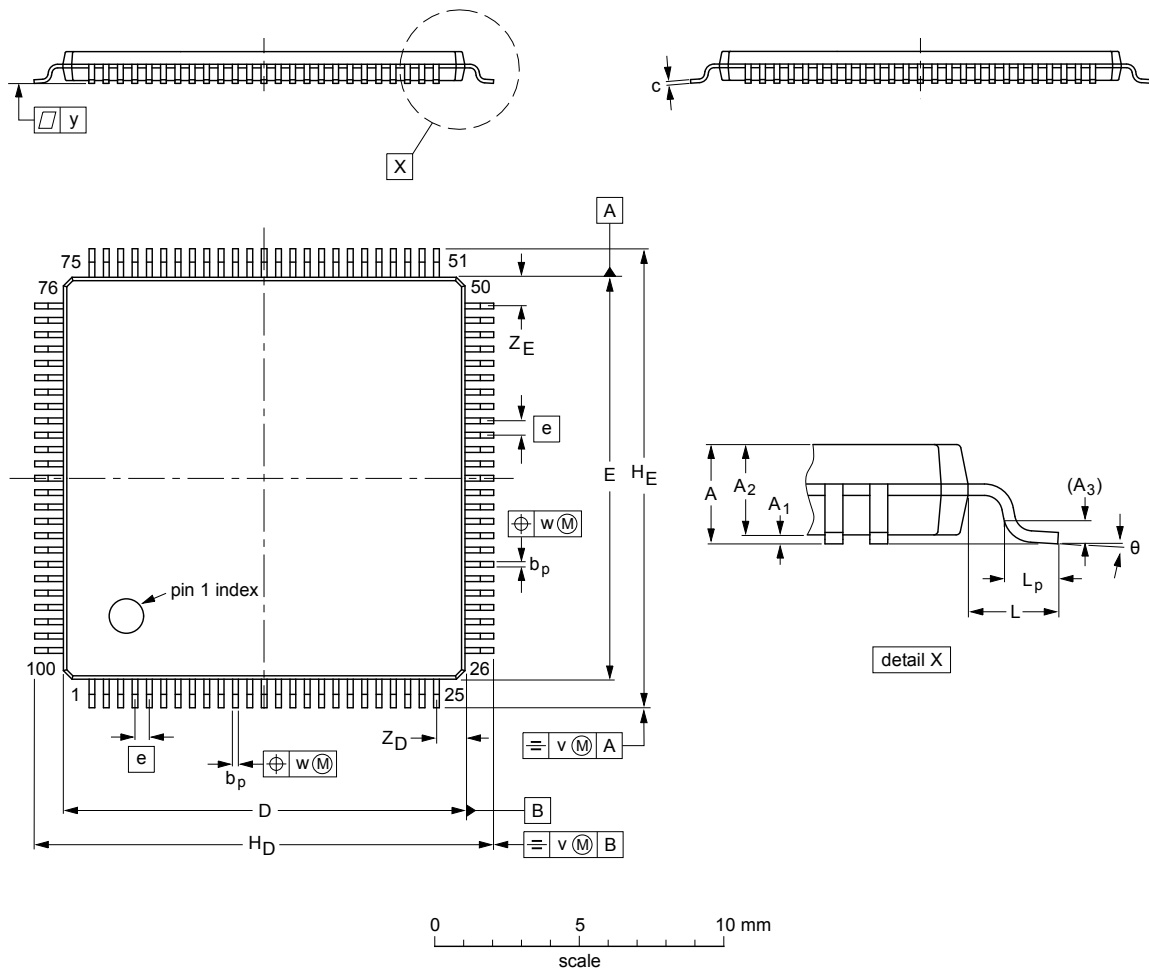
Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	13.9	-	14	14.1	mm
E	package width	13.9	-	14	14.1	mm
A	seated height	[tbd]	-	1.2	1.2	mm
A <sub>2</sub>	package height	0.95	-	1	1.05	mm
n <sub>2</sub>	actual quantity of termination	-	-	100	-	



2. Package outline

TQFP100: plastic thin quad flat package; 100 leads; body 14 x 14 x 1 mm

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DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A <sub>1</sub>	A <sub>2</sub>	A <sub>3</sub>	b <sub>p</sub>	c	D <sup>(1)</sup>	E <sup>(1)</sup>	e	H <sub>D</sub>	H <sub>E</sub>	L	L <sub>p</sub>	v	w	y	Z <sub>D</sub> <sup>(1)</sup>	Z <sub>E</sub> <sup>(1)</sup>	θ
mm	1.2	0.15 0.05	1.05 0.95	0.25	0.27 0.17	0.18 0.12	14.1 13.9	14.1 13.9	0.5	16.15 15.85	16.15 15.85	1	0.75 0.45	0.2	0.08	0.08	1.15 0.85	1.15 0.85	7° 0°

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES			EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA		
SOT386-1	137E20	MS-026			-00-01-19 03-02-25

Fig. 1. Package outline TQFP100 (SOT386-1)

### 3. Soldering

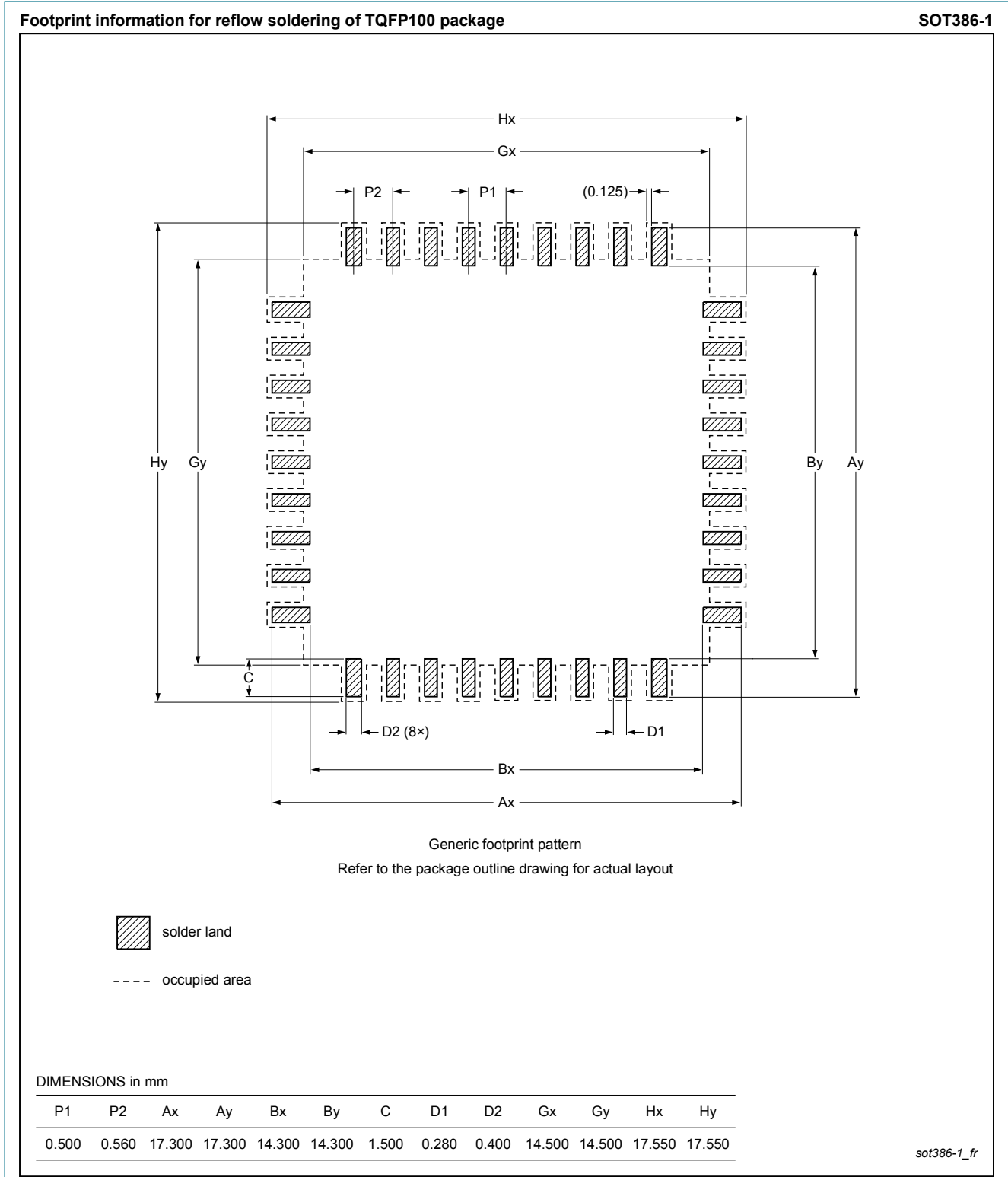


Fig. 2. Reflow soldering footprint for TQFP100 (SOT386-1)

## 4. Legal information

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